



THE LHCB VELO UPGRADE PROGRAMME FOR HIGH LUMINOSITY RUNNING AT THE LHC AND HL-LHC

T. Evans, On behalf of the LHCb Velo group ICHEP 2020 $\,$

High Luminosity LHC



- HL-LHC will increase luminosity for LHCb by a factor of 7.5 from Upgrade-I.
- \triangleright 7.5× radiation damage, multiplicity, data rates and track density.
- ▷ Improvements to the detector needed to maintain the physics performance.
- ▷ Upgraded Sensors, ASICs and mechanics needed to survive rates and doses.

Huge amount of physics can be done with all of this data:



LHCb Upgrade II Expression of interest (CERN-LHCC-2017-003)





Opportunities in flavour physics, and beyond, in the HL-LHC era Physics case for an LHCb Upgrade II (LHCb-PUB-2018-009)

1/18

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Physics case for an LHCb Upgrade II (LHCb-PUB-2018-009)

The Phase II Upgrade challenge



Some idea of what the (very challenging) requirements for the detector will be:

	Classic	Upgrade I	Upgrade II	
Luminosity / year $[fb^{-1}]$	2	7	~ 50	
Pileup	1.8	7	~ 50	Can we readout and re- construct with this much pileup?
Integ. Fluence $[1 \cdot \text{MeV}n_{eq}/cm^2]$ (@8.2mm for classic, @ 5.1mm for U-I/II)	4.3×10^{14}	8×10^{15}	$\sim 6\times 10^{16}$	Will the detector require regular replacements?
$\begin{array}{c} {\rm Readout} {\rm rate} ({\rm hottest} {\rm chip}) \\ \left[10^6 {\rm hits/s} \right] \end{array}$		600	~ 4500	

At these intensities, flexibility and power of hybrid pixels is still essential. But otherwise what kind of detector can meet this challenge?

$\label{eq:Vertex} \mbox{ Reconstruction } @ \ \mu \ \sim 50 \\ \mbox{ The Phase II Upgrade Challenge} \\ \label{eq:Vertex}$



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- $\triangleright\,$ Each bunch crossing is very busy in U-II conditions.
- ▷ But, the proton bunches overlap for a finite time (RMS $\sim 180 \text{ ps}$) \rightarrow what if we could resolve them in time (within each crossing) as well space?

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- ▷ Each bunch crossing is very busy in U-II conditions.
- \triangleright But, the proton bunches overlap for a finite time (RMS ~ 180 ps) \rightarrow what if we could resolve interactions in time (within each crossing) as well space?
- \triangleright Looks a lot better in slices of time \rightarrow need but will need excellent temporal resolution (10s of ps per hit).



- \triangleright At ~ 50 interactions / bunch crossing, PV separation is comparable to the per-track pointing resolution to the beam axis (~ 1 mm) : Reconstruction becomes tough.
- ▷ Initial studies show adding 50 ps / hit timestamp almost completely recovers the Upgrade-I vertex reconstruction efficiency.

4D Tracking The Phase II Upgrade Challenge



Four-dimensional tracking brings improvements to:

- ▷ Tracking efficiency and its spatial uniformity, important for control of systematic uncertainties as correlated with decay times.
- $\triangleright\,$ Large reduction in ghost rate (down to $\sim 1\%).$

Studies ongoing of 4D tracking on CPU, GPUs and FPGAs.

The Phase II Upgrade challenge

- Timing in the VELO is mandatory in HL conditions for the reconstruction of vertices.
- \triangleright Could a per-track measurement (i.e. a timing plane with a more precise ~ 30 ps timestamp) work?
- × Only plausible to cover ~ LHCb acceptance: no timing for VELO only tracks.
- $\times\,$ Lose the substantial benefits to track reconstruction.
- × Time-of-flight differences a problem if plane is $@ \sim 1m$.
- × Could have large pixels, but then the higher occupancy may be a problem.
- × Would require the development of two readout ASICs (one for VELO, one for timing plane)



A full, four-dimensional detector is clearly the preferred solution. So how do we get there?

Future ASIC requirements First steps towards a 4D Vertex Locator

	VeloPix (2016)	Timepix4 (2018/9)	Picopix? (2024)?
Technology [nm]	130	65	< 65
Pixel Size [µm]	$55 \times 55 \mu m$	$55 \times 55 \mu m$	$55 \times 55 \mu m$?
Pixels	256×256	512×448	$256 \times 256?$
Area [cm ²]	1.98	6.94	1.98
Event packet [bit]	24	64	64?
Max. Rate [10 ⁶ Hits/cm ² /s]	~ 400	~ 180	$\sim 4000?$
Time resolution (TDC)	$25\mathrm{ns}$	$200 \mathrm{ps}$	20 - 50 ps?
Readout bandwidth $[Gb/s]$	19.2	≤ 81.92	$\sim 500?$





VeloPix ASIC

- $\triangleright\,$ VeloPix ASIC for Upgrade I developed in collaboration with the Medipix group.
- $\triangleright~$ The Timepix4 is the next generation, with already impressive fast timing at $\sim 200~{\rm ps.}$
- $\triangleright~$ Can the next-to-next generation (Picopix?) get us to $20 \rightarrow 50\,\mathrm{ps?}$
- ▷ Other requirements (i.e. data rates) on the chip also extremely demanding.

Timepix4 has arrived!



Sensors

Will require a very fast ($\sigma \sim 10 \rightarrow 50 \text{ ps}$) sensor as well as readout ASIC. Some possibilities:

Low Gain Avalanche Detectors (LGADs)

▷ Excellent time resolution.



3D sensors

▷ 3D sensors optimised for timing measurements by the TimeSpot collaboration.



- $\triangleright~$ But low fill factors for small pixels.
- $\triangleright~$ And probably not radiation hard enough.
- $\triangleright\,$ R&D ongoing to see if these factors can be overcome.
- ▷ Also excellent timing resolution (~ 15 ps) demonstrated.
- ▷ But also has inactive areas \rightarrow can detector design mitigate their impact?

CERN EP R&D



- ▷ General interest for fast-timing detectors from CERN for next generation experiments, FCC, BDF, ...
- ▷ One of the 11 WPs for CERN detector R&D dedicated to novel hybrid silicon detectors (WP1.1)

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- \triangleright Example activities include building test bench β sources and weighting-field simulation.





Mechanical Design and Radiation Damage

- ▷ The radiation damage at the inner edge of the detector is enormous, $\sim 10^{16} 1 \,\mathrm{MeV} n_{\mathrm{eq}}/\mathrm{cm}^2$ every year of operation.
- ▷ This is about the fluence where planar sensors are basically useless. Will the detector need to be replaced regularly or is there another option?
- Fluence varies strongly as a function of the distance to the luminous region. Could the detector be moved further away?
- ▷ Why is the VELO so close to the interaction region in the first place? \rightarrow driven by impact parameter resolution.
- ▷ So, can we optimise the other detector parameters (hit resolution, material) to maintain the performance but at lower fluence?



- ▷ Yes: Moving to ~ 12 mm we get the same integrated fluence as U-I.
- \triangleright **But:** would need to drastically reduce the material (the RF foil, but also the modules) and reduce the pixel pitch to $\sim 40 \,\mu\text{m}$ from 55 μm .

Mechanics

Replaceable detectors to deal with extreme integrated fluence?



Detector cassettes that can be swapped during technical stops?

RF foil separates detector from LHC primary vacuum Can it be simplified? Thinned? Removed entirely?



Once concept: Support a very thin $(\sim 20\,\mu\text{m})$ foil using the modules themselves.

Cooling

Different ideas for providing cooling to the modules

- $\triangleright\,$ Modules must be kept cold to prevent thermal runaway caused by leakage current after sensors are irradiated.
- \triangleright Upgrade I uses biphase CO_2 cooling, provided by silicon microchannel plates. Should we do something different for Upgrade-II?



▷ Much smaller microchannel plates to mitigate cost?

16/18

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17/18

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▷ Already prototyped for Upgrade-I.

Conclusions

- \triangleright Precise timing in the VELO will be essential to maintain (or improve!) physics performance with pileup of \sim 50.
- ▷ Radiation environment for the detector will be extremely challenging, but several different strategies to deal with this on the table.
- \triangleright Much work to be done on the ASIC design, but the path forward is clear.
- $\triangleright~$ Lots of different ideas for how to achieve sensors with sufficient time resolution.
- ▷ The mechanical design and cooling are also crucial, particularly if detector will have to be replaced multiple times.
- ▷ No specific choices of technlogies are ruled in or out.